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PATENT
Attorney Docket No.: COOL-02100

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	Group Art Unit: 3753
Douglas Werner et al.)	Examiner:
Serial No.: 10/769,717)	<u>TRANSMITTAL LETTER</u>
Filed: January 29, 2004)	162 N. Wolfe Road
For: HERMETIC CLOSED LOOP)	Sunnyvale, CA 94086
FLUID SYSTEM)	(408) 530-9700
)	Customer No.: 28960

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

Enclosed please find an Information Disclosure Statement and Form PTO-1449, including copies of the references contained thereon, for filing in the U.S. Patent and Trademark Office.

You will also find enclosed the associated Transmittals, Electronic Information Disclosure Statements, and United States Patent and Trademark Office Acknowledgment Receipts for the electronically filed Information Disclosure Statement (EFS ID #200407141632055371570343502050701044); (EFS ID #64520); and (EFS ID #64521) filed on July 14, 2004.

The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 7-14-04

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CERTIFICATE OF MAILING (37 CFR § 1.8(a))

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to the: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450

HAVERSTOCK & OWENS LLP
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Filed: January 29, 2004)	<u>STATEMENT</u>
For: HERMETIC CLOSED LOOP FLUID SYSTEM)	162 N. Wolfe Road Sunnyvale, CA 94086 (408) 530-9700

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Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #200407141632055371570343502050701044); (EFS ID #64520); and (EFS ID #64521). Applicants have become aware of the following printed publication which may be material to the examination of this application:

- Chinese Publication No. CN 97212126.9;
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This Information Disclosure Statement under 37 C.F.R. §§ 1.56 and 1.97 is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that anyone or more of these citations constitutes prior art.

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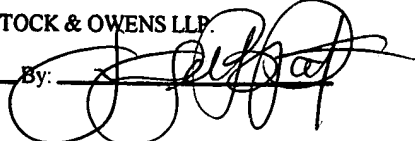
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(37 CFR § 1.98(b))

Filing Date: January 29, 2004

Group Art Unit: 3753

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Examiner:

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)				Applicants: Douglas Werner et al.	
(37 CFR § 1.98(b))				Filing Date: January 29, 2004	Group Art Unit: 3753
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Title of Invention	HERMETIC CLOSED LOOP FLUID SYSTEM						
Application Number:	10/769717						
Confirmation Number:	8804						
First Named Applicant:	Douglas Werner						
Attorney Docket Number:							
Search string:	(3654988 or 3817321 or 3823572 or 3923426 or 3929154 or 4109707 or 4194559 or 4248295 or 4485429 or 4561040 or 4664181 or 4866570 or 4894709 or 4896719 or 4908112 or 5009760 or 5058627 or 5070040 or 5088005 or 5096388 or 5099311 or 5099910 or 5125451 or 5131233 or 5203401 or 5218515 or 5219278 or 5232047 or 5239200 or 5263251 or 5274920 or 5309319 or 5317805 or 5325265 or 5336062 or 5380956 or 5383340 or 5427174 or 5436793 or 5514906 or 5544696 or 5548605 or 5579828 or 5585069 or 5641400 or 5692558 or 5696405 or 5703536 or 5704416 or 5727618).pn.						
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